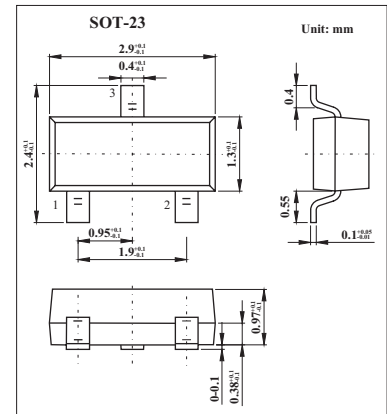


BZX84C2V7

Features

- Planar Die Construction
- 350mW Power Dissipation
- Ideally Suited for Automated Assembly Processes



Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Forward Voltage at $I_F = 10\text{ mA}$	V_F	0.9	V
Power Dissipation *	P_D	350	mW
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_s	-65 to + 150	$^\circ\text{C}$
Thermal Resistance Junction to Ambient Air *	R_{thA}	417	$^\circ\text{C/W}$

*Device mounted on FR-4 PC board with recommended pad layout,

Electrical Characteristics $T_a = 25^\circ\text{C}$ (unless otherwise noted)

Type Number	Zener Voltage Range *1				Maximum Zener Impedance *2			Maximum Reverse Current *1		Typical Temperature Coefficient @ I_{ZT} mV/ $^\circ\text{C}$	
	V_Z @ I_{ZT}			I_{ZT}	Z_{ZT} @ I_{ZT}	Z_{ZK} @ I_{ZK}		I_R	V_R	Min	Max
	Nom (V)	Min (V)	Max (V)	mA	Ω	Ω	mA	μA	V		
BZX84C2V7	2.7	2.5	2.9	5.0	100	600	1.0	20	1	-3.5	0

*1. Short duration test pulse used to minimize self-heating effect.

*2. $f = 1\text{ KHz}$.

Marking

Marking	Z12
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BZX84C2V7

